

XP-002318727

(C) WPI/Derwent

AN - 1999-199070 [17]

AP - JP19970203280 19970729

CPY - MITC

DC - A85 L03 P81 V07 V08

FS - CPI;GMPI;EPI

IC - B01J19/00 ; C01G11/02 ; C01G23/04 ; C08J3/20 ; C08K9/04 ; C08L101/00 ; G02F1/35

**MC - A08-M09A A09-A03 A12-E01 A12-L03 L03-D L04-A
- V07-K10 V08-A04X**

PA - (MITC) MITSUI PETROCHEM IND CO LTD

PN - JP11043556_A 19990216 DW199917 C08K9/04 007pp

PR - JP19970203280 19970729

XA - C1999-058263

XIC - B01J-019/00 ; C01G-011/02 ; C01G-023/04 ; C08J-003/20 ; C08K-009/04 ; C08L-101/00 ; G02F-001/35

XP - N1999-147074

AB - J11043556 NOVELTY - The resin material contains ultra small semiconductor particles, the surface of which undergoes a prior treatment by reaction with a compound containing one or more functional groups.

- DETAILED DESCRIPTION - An INDEPENDENT CLAIM is also included for the manufacturing method of surface treated semiconductor particle content resin material.

- USE - For electronic materials such as optical devices, refractive index adjusting devices, optical-electronic sensing element, phase conjugation wave generating unit, super lattice device, wavelength cut-off filter, magnetic recording, optical registration etc.

- ADVANTAGE - Enables uniform dispersion of the semiconductor ultra small particle in the resin material and the diameter and particle size distributions are controlled.

- (Dwg.0/4)

**IW - SURFACE TREAT SEMICONDUCTOR PARTICLE CONTENT RESIN MATERIAL
SEMICONDUCTOR PARTICLE TREAT COMPOUND CONTAIN ONE MORE FUNCTION GROUP**

PRIOR DISPERSE RESIN MATERIAL

**IKW - SURFACE TREAT SEMICONDUCTOR PARTICLE CONTENT RESIN MATERIAL
SEMICONDUCTOR PARTICLE TREAT COMPOUND CONTAIN ONE MORE FUNCTION GROUP**

PRIOR DISPERSE RESIN MATERIAL

NC - 001

OPD - 1997-07-29

ORD - 1999-02-16

PAW - (MITC) MITSUI PETROCHEM IND CO LTD

TI - Surface treated semiconductor particle content resin material - has semiconductor particles which are treated with compound containing one or more functional groups prior to dispersion in resin material